

# SHENZHEN MENGKE ELECTRONICS TECHNOLOGY CO.,LTD TO-252/251 Plastic-Encapsulate MOSFETS

SYMBOL:

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# MKFR5410P P-Channel 100-V(D-S) Power MOSFET

V(BR)DSS	RDS(on)MAX	ID
-100 V	205mΩ@ -10 V	-13A

### **General Description:**

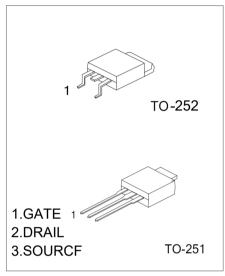
Fifth Generation HEXFETs from International Rectifierutilize advanced processing techniques to achieveextremely low on-resistance per silicon area. This benefit, combined with the fast switching speed and ruggedizeddevice design that HEXFET Power MOSFETs are wellknown for, provides the designer with an extremely efficientand reliable device for use in a wide variety of applications.

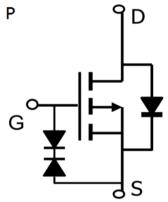
The D-Pak is designed for surface mounting using vaporphase, infrared, or wave soldering techniques. The straightlead version (MKFU series) is for through-hole mountingapplications. Power dissipation levels up to 1.5 watts are possible in typical surface mount applications.

#### **FEATURE:**

- Ultra Low On-Resistance
- Surface Mount (MKFR5410)
- Straight Lead (MKFU5410)
- Advanced Process Technology
- Fast Switching
- Fully Avalanche Rated
- ESD: 2KV/HBM

## **Equivalent Circuit:**





## Maximum ratings ( Ta=25℃ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	VDS	-100	V
Gate-Source Voltage	VGS	±20	<b>V</b>
Continuous Drain Current	ID	-13	Α
Pulsed Diode Curren	IDM	-52	A
Power Dissipation	PD	66	W
Single Pulse Avalanche Energy	EAS	194	mJ
Avalanche Current	IAR	-8.4	Α
Repetitive Avalanche Energy	EAR	6.3	mJ
Peak Diode Recovery dv/dt	dv/dt	-5.0	V/ns
Thermal Resistance from Junction to Ambient (t≤10s)	RθJA	110	℃/ <b>W</b>
Operating Junction	TJ	150	<b>°</b> C
Storage Temperature	TSTG	-55~+150	°C



## SHENZHEN MENGKE ELECTRONICS TECHNOLOGY CO.,LTD

#### MOSFET ELECTRICAL CHARACTERISTICS

#### Static Electrical Characteristics (Ta = 25 ℃ Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit	
Static							
Drain-source breakdown voltage	V(BR)DSS	VGS = 0V, ID = -250μA	-100			V	
Gate-source threshold voltage	VGS(th)	VDS =VGS, ID = -250μA	-2		-4	V	
Gate-source leakage	IGSS	VDS =0V, VGS = ±20V			±10	μΑ	
Zero gate voltage drain current	IDSS	VDS = -100V, VGS =0V			-25	μA	
Drain-source on-state resistancea	RDS(on)	VGS = -10V, ID = -7.8A		198	205	mΩ	
Forward transconductancea	gfs	VDS = -50V, ID = -7.8A	3.2			s	
Diode forward voltage	VSD	IS= -2A, VGS=0V		-0.75	-1.1	٧	
Dynamic				Į.			
Input capacitance	Ciss			760		рF	
Output capacitance	Coss	VDS = -25V,VGS =0V, f=1MHz		260		pF	
Reverse transfer capacitanceb	Crss			170		pF	
Total gate charge	Qg				58	nC	
Gate-source charge	Qgs	VDS = -80V,VGS = -10V, ID = -8.4A			8.3	nC	
Gate-drain charge	Qgd	.5 0			32	nC	
Switchingb		1					
Turn-on delay time	td(on)			15		ns	
Rise time	tr	VDS= -50V		58		ns	
Turn-off delay time	td(off)	RL= $10\Omega$ , ID = -8.4A, VGEN= -10V,Rg= $9\Omega$		45		ns	
Fall time	tf			46		ns	
Drain-Source Diode Characte	ristics						
Continuous Source-Drain Diode Current	IS				-13	Α	
Pulsed Diode forward Curren	ISM		_		-52	Α	
Reverse Recovery Time	trr	IF = -8.4A, di/dt = 100A/μs		130	190	ns	
Reverse Recovery Charge	Qrr	IF = -8.4A, di/dt = 100A/μs		650	970	nC	

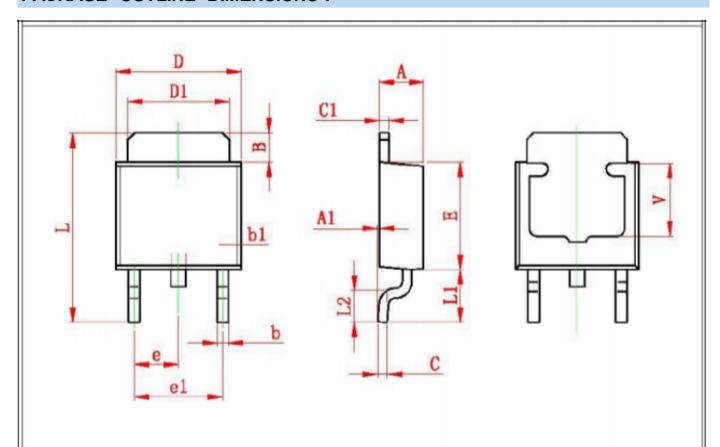
#### Note:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t < 10 sec.
- 3. Pulse Test : Pulse Width≤300µs, Duty Cycle ≤ 2%.
- 4. Starting TJ =  $25 \times C$ , L = 6.4 mH RG = 25 W, IAS = -7.8 A. (See Figure 12)
- 5. ISD ≤ -7.8A, di/dt ≤ 200A/ $\mu$ s, VDD ≤ V(BR)DSS,TJ ≤ 150 °C
- 6. This is applied for I-PAK, LS of D-PAK is measured between lead and center of die contact



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# PACKAGE OUTLINE DIMENSIONS:

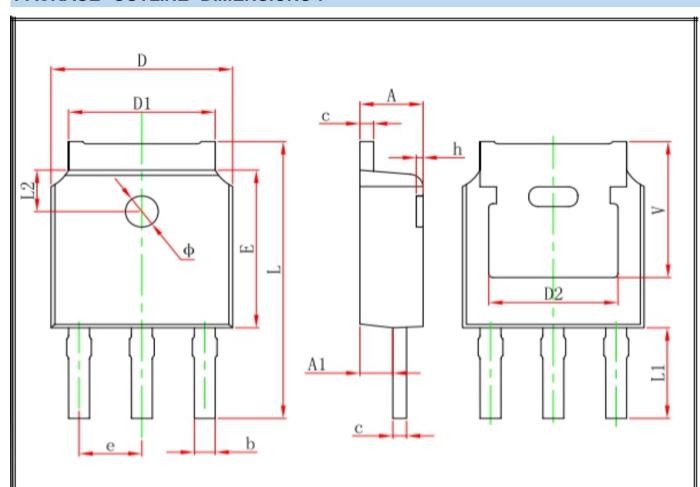


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
Α	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
В	1.350	1.650	0.053	0.065
b	0.500	0.700	0.020	0.028
b1	0.700	0.900	0.028	0.035
С	0.430	0.580	0.017	0.023
c1	0.430	0.580	0.017	0.023
D	6.350	6.650	0.250	0.262
D1	5.200	5.400	0.205	0.213
E	5.400	5.700	0.213	0.224
е	2.300 TYP		0.091 TYP	
e1	4.500	4.700	0.177	0.185
L	9.500	9.900	0.374	0.390
L1	2.550	2.900	0.100	0.114
L2	1.400	1.780	0.055	0.070
V	3.80 REF		0.150 REF	



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## **PACKAGE OUTLINE DIMENSIONS:**



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	2.200	2.400	0.087	0.094	
A1	0.860	1.160	0.034	0.046	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	4.830 REF.		0.190 REF.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	10.400	11.000	0.409	0.433	
L1	3.300	3.700	0.130	0.146	
L2	1.600 REF.		0.063 REF.		
Φ	1.100	1.300	0.043	0.051	
h	0.000	0.300	0.000	0.012	
V	5.350 REF.		0.211	REF.	